# MOSFET – Power, N-Channel, SUPERFET III, FRFET

## **650 V, 36 A, 95 m**Ω

## Description

SUPERFET III MOSFET is ON Semiconductor's brand-new high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low on-resistance and lower gate charge performance. This advanced technology is tailored to minimize conduction loss, provide superior switching performance, and withstand extreme dv/dt rate.

Consequently, SUPERFET III MOSFET is very suitable for the various power system for miniaturization and higher efficiency.

SUPERFET III FRFET MOSFET's optimized reverse recovery performance of body diode can remove additional component and improve system reliability.

### Features

- 700 V @ T<sub>J</sub> = 150°C
- Typ.  $R_{DS(on)} = 82 \text{ m}\Omega$
- Ultra Low Gate Charge (Typ.  $Q_g = 66 \text{ nC}$ )
- Low Effective Output Capacitance (Typ. Coss(eff.) = 569 pF)
- 100% Avalanche Tested
- These Devices are Pb-Free and are RoHS Compliant

### Applications

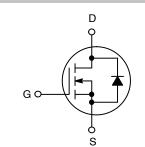
- Telecom / Server Power Supplies
- Industrial Power Supplies
- EV Charger
- UPS / Solar

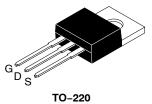


## **ON Semiconductor®**

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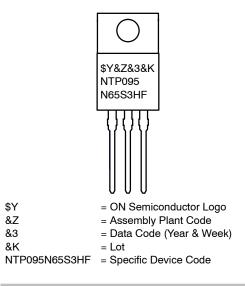
V <sub>DSS</sub>	R <sub>DS(ON)</sub> MAX	I <sub>D</sub> MAX		
650 V	95 mΩ @ 10 V	36 A		





CASE 340AT

### MARKING DIAGRAM



**ORDERING INFORMATION** 

See detailed ordering and shipping information on page 2 of this data sheet.

Symbol	Parameter		Value	Unit	
V <sub>DSS</sub>	Drain to Source Voltage		650	V	
V <sub>GSS</sub>	Gate to Source Voltage	– DC	±30	V	
		– AC (f > 1 Hz)	±30		
Ι <sub>D</sub>	Drain Current	– Continuous (T <sub>C</sub> = 25°C)	36	А	
		– Continuous (T <sub>C</sub> = 100°C)	22.8		
I <sub>DM</sub>	Drain Current - Pulsed (Note 1)		90	А	
E <sub>AS</sub>	Single Pulsed Avalanche Energy (Note 2)		440	mJ	
I <sub>AS</sub>	Avalanche Current (Note 2)		4.6	А	
E <sub>AR</sub>	Repetitive Avalanche Energy (Note 1)		2.72	mJ	
dv/dt	MOSFET dv/dt		100	V/ns	
	Peak Diode Recovery dv/dt (Note 3)		50		
P <sub>D</sub>	Power Dissipation	(T <sub>C</sub> = 25°C)	272	W	
		– Derate Above 25°C	2.176	W/°C	
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range		-55 to +150	°C	
ΤL	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 seconds		300	°C	

#### ABSOLUTE MAXIMUM RATINGS (T<sub>C</sub> = 25°C, Unless otherwise noted)

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality shows be assumed, damage may occur and reliability may be affected. 1. Repetitive rating: pulse-width limited by maximum junction temperature. 2.  $I_{AS} = 4.6 \text{ A}, R_G = 25 \Omega$ , starting  $T_J = 25^{\circ}\text{C}$ . 3.  $I_{SD} \le 18 \text{ A}, \text{ di/dt} \le 200 \text{ A/}\mu\text{s}, \text{ V}_{DD} \le 400 \text{ V}, \text{ starting } T_J = 25^{\circ}\text{C}$ .

### **THERMAL CHARACTERISTICS**

Symbol	Parameter	Value	Unit
$R_{ ext{ heta}JC}$	Thermal Resistance, Junction to Case, Max.	0.46	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max.	62.5	

#### PACKAGE MARKING AND ORDERING INFORMATION

Part Number	Top Marking	Package	Packing Method	Reel Size	Tape Width	Quantity
NTP095N65S3HF	NTP095N65S3HF	TO-220	Tube	N/A	N/A	50 Units

## ELECTRICAL CHARACTERISTICS (T<sub>C</sub> = 25°C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
OFF CHARACT	ERISTICS					
BV <sub>DSS</sub>	Drain to Source Breakdown Voltage	$V_{GS}$ = 0 V, $I_D$ = 1 mA, $T_J$ = 25°C	650			V
		$V_{GS}$ = 0 V, I <sub>D</sub> = 1 mA, T <sub>J</sub> = 150°C	700			V
$\Delta \text{BV}_{\text{DSS}} / \Delta \text{T}_{\text{J}}$	Breakdown Voltage Temperature Coefficient	$I_D$ = 15 mA, Referenced to 25°C		0.63		V/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	$V_{DS}$ = 650 V, $V_{GS}$ = 0 V			10	μA
		$V_{DS}$ = 520 V, $T_{C}$ = 125°C		97		
I <sub>GSS</sub>	Gate to Body Leakage Current	$V_{GS}$ = ±30 V, $V_{DS}$ = 0 V			±100	nA
N CHARACTE	RISTICS					
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_D = 0.86 \text{ mA}$	3.0		5.0	V
R <sub>DS(on)</sub>	Static Drain to Source On Resistance	$V_{GS}$ = 10 V, I <sub>D</sub> = 18 A		82	95	mΩ
9 <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = 20 V, I <sub>D</sub> = 18 A		22		S
YNAMIC CHA	RACTERISTICS		•			
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = 400 V, V <sub>GS</sub> = 0 V, f = 1 MHz		2930		pF
Coss	Output Capacitance			61		pF
C <sub>oss(eff.)</sub>	Effective Output Capacitance	$V_{DS}$ = 0 V to 400 V, $V_{GS}$ = 0 V		569		pF
Coss(er.)	Energy Related Output Capacitance	$V_{DS}$ = 0 V to 400 V, $V_{GS}$ = 0 V		110		pF
Q <sub>g(tot)</sub>	Total Gate Charge at 10V			66		nC
Q <sub>gs</sub>	Gate to Source Gate Charge	V <sub>DS</sub> = 400 V, I <sub>D</sub> = 18 A, V <sub>GS</sub> = 10 V (Note 4)		21		nC
Q <sub>gd</sub>	Gate to Drain "Miller" Charge	(1000 4)		25		nC
ESR	Equivalent Series Resistance	f = 1 MHz		2.4		Ω
WITCHING CH	IARACTERISTICS					
t <sub>d(on)</sub>	Turn-On Delay Time			28		ns
t <sub>r</sub>	Turn-On Rise Time	$V_{DD} = 400 \text{ V}, \text{ I}_{D} = 18 \text{ A},$		28		ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{GS} = 10 \text{ V}, \text{ R}_{g} = 4.7 \Omega$ (Note 4)		72		ns
t <sub>f</sub>	Turn-Off Fall Time			24		ns
OURCE-DRAI	N DIODE CHARACTERISTICS					
I <sub>S</sub>	Maximum Continuous Source to Drain Diode Forward Current				36	Α
I <sub>SM</sub>	Maximum Pulsed Source to Drain Diode Forward Current				90	Α
V <sub>SD</sub>	Source to Drain Diode Forward Voltage	V <sub>GS</sub> = 0 V, I <sub>SD</sub> = 18 A			1.3	V
t <sub>rr</sub>	Reverse Recovery Time	V <sub>DD</sub> = 400 V, I <sub>SD</sub> = 18 A,		106		ns
Q <sub>rr</sub>	Reverse Recovery Charge	$dI_F/dt = 100 A/\mu s$		414		nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 4. Essentially independent of operating temperature typical characteristics.

## **TYPICAL CHARACTERISTICS**

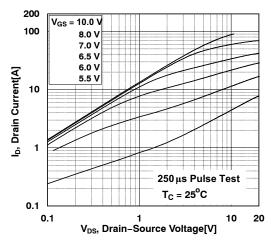


Figure 1. On–Region Characteristics

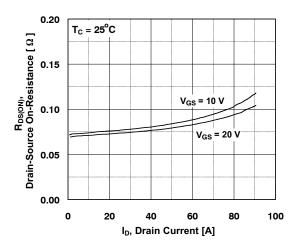
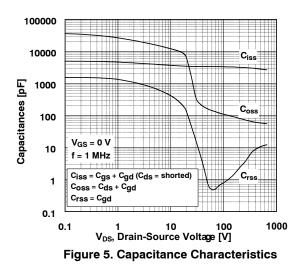


Figure 3. On–Resistance Variation vs. Drain Current and Gate Voltage



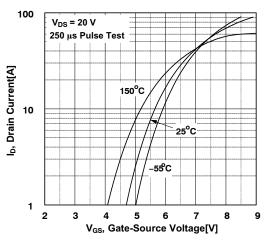


Figure 2. Transfer Characteristics

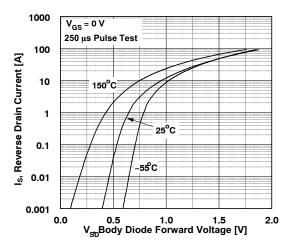


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

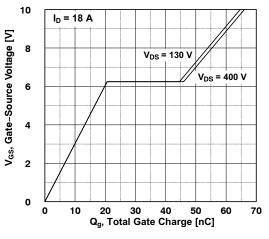
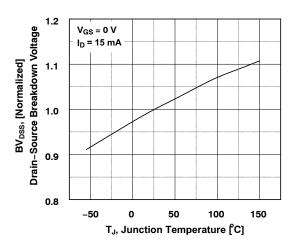
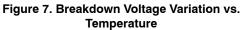


Figure 6. Gate Charge Characteristics

## **TYPICAL CHARACTERISTICS**





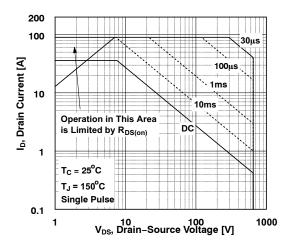


Figure 9. Maximum Safe Operating Area

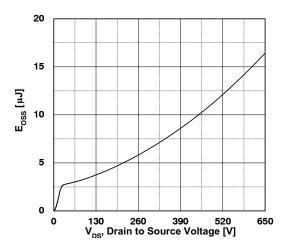


Figure 11. Eoss vs. Drain-to-Source Voltage

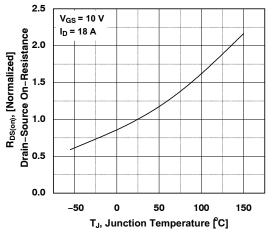


Figure 8. On–Resistance Variation vs. Temperature

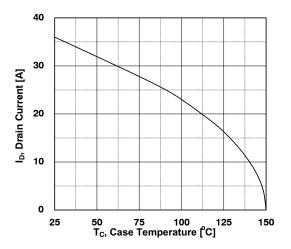


Figure 10. Maximum Drain Current vs. Case Temperature

## **TYPICAL CHARACTERISTICS**

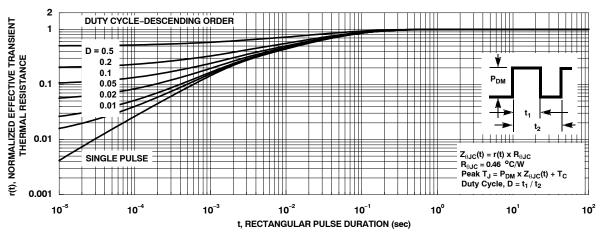


Figure 12. Transient Thermal Response Curve

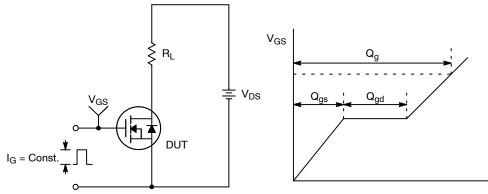


Figure 13. Gate Charge Test Circuit & Waveform

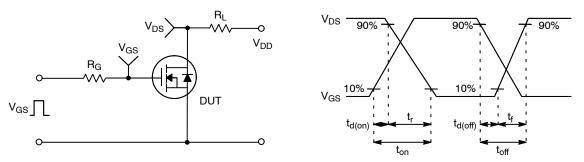


Figure 14. Resistive Switching Test Circuit & Waveforms

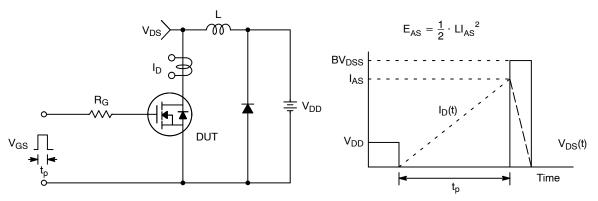
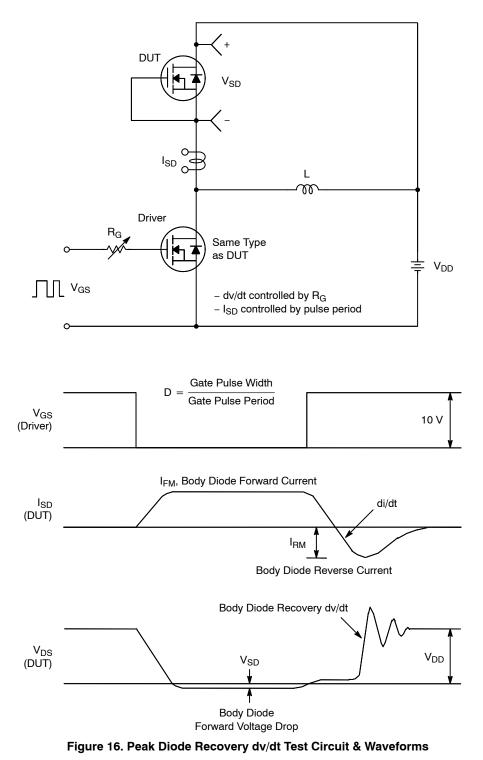
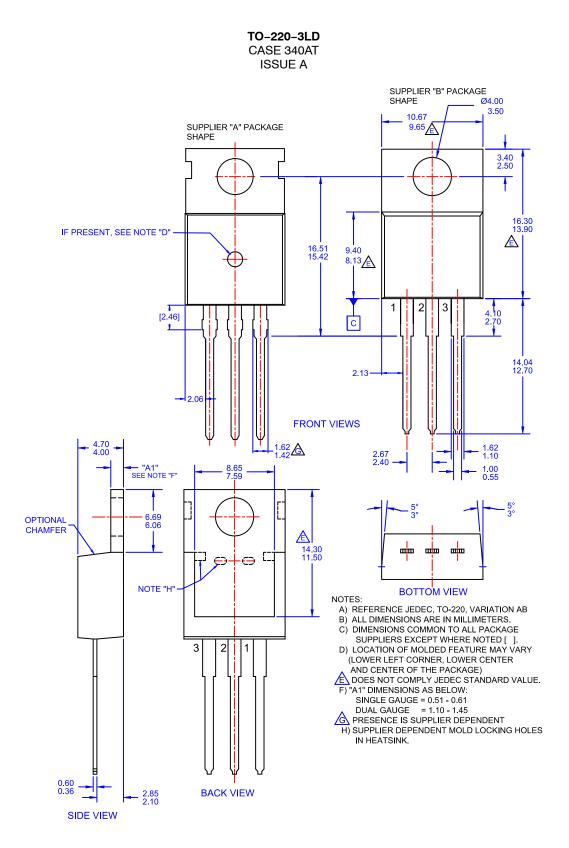


Figure 15. Unclamped Inductive Switching Test Circuit & Waveforms



### PACKAGE DIMENSIONS



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